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December 2013

# **FDH44N50**

# N-Channel SMPS Power MOSFET 500 V, 44 A, 120 m $\Omega$

### **Features**

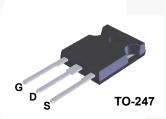
- ullet Low Gate Charge  $Q_g$  Results in Simple Drive Requirement (Typ. 90 nC)
- Improved Gate, Avalanche and High Reapplied dv/dt Ruggedness
- Reduced  $R_{DS(on)}$  (110 m $\Omega$  (Typ.) @  $V_{GS}$  = 10 V,  $I_D$  = 22 A)
- Reduced Miller Capacitance and Low Input Capacitance (Typ.  $C_{rss}$  = 40 pF)
- Improved Switching Speed with Low EMI
- 175°C Rated Junction Temperature

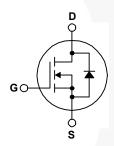
# Description

UniFET™ MOSFET is Fairchild Semiconductor's high voltage MOSFET family based on planar stripe and DMOS technology. This MOSFET is tailored to reduce on-state resistance, and to provide better switching performance and higher avalanche energy strength. This device family is suitable for switching power converter applications such as power factor correction (PFC), flat panel display (FPD) TV power, ATX and electronic lamp ballasts.

### **Applications**

- Lighting
- Uninterruptible Power Supply
- AC-DC Power Supply





# Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted.

| Symbol                                             | Parameter                                                    | FDH44N50              | Unit |  |
|----------------------------------------------------|--------------------------------------------------------------|-----------------------|------|--|
| V <sub>DSS</sub>                                   | Drain to Source Voltage                                      | 500                   | V    |  |
| V <sub>GS</sub>                                    | Gate to Source Voltage                                       | ±30                   | V    |  |
| I <sub>D</sub>                                     | Drain Current                                                |                       |      |  |
|                                                    | Continuous ( $T_C = 25^{\circ}C$ , $V_{GS} = 10 \text{ V}$ ) | 44                    | Α    |  |
|                                                    | Continuous ( $T_C = 100$ °C, $V_{GS} = 10 \text{ V}$ )       | 32                    | Α    |  |
|                                                    | Pulsed <sup>1</sup>                                          | 176                   | Α    |  |
| P <sub>D</sub> Power Dissipation Derate Above 25°C | Power Dissipation                                            | 750                   | W    |  |
|                                                    | Derate Above 25°C                                            | 5                     | W/ºC |  |
| Γ <sub>J</sub> , Τ <sub>STG</sub>                  | Operating and Storage Temperature                            | -55 to 175            | °C   |  |
|                                                    | Soldering Temperature for 10 Seconds                         | 300 (1.6mm from case) | °C   |  |
|                                                    | Mounting Torque, 8-32 or M3 Screw                            | 10ibf*in (1.1N*m)     |      |  |

### **Thermal Characteristics**

| Symbol          | Parameter                                     | FDH44N50 | Unit |  |
|-----------------|-----------------------------------------------|----------|------|--|
| $R_{\theta JC}$ | Thermal Resistance, Junction-to-Case, Max.    | 0.2      | °C/W |  |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient, Max. | 40       | °C/W |  |

# **Package Marking and Ordering Information**

| Part Number | Top Mark | Package | Packing Method | Reel Size | Tape Width | Quantity |
|-------------|----------|---------|----------------|-----------|------------|----------|
| FDH44N50    | FDH44N50 | TO-247  | Tube           | N/A       | N/A        | 30 units |

### **Flectrical Characteristics**

| Symbol                                  | Parameter                                            | Test Con                                                                                 | ditions                          | Min.  | Тур. | Max. | Uni  |
|-----------------------------------------|------------------------------------------------------|------------------------------------------------------------------------------------------|----------------------------------|-------|------|------|------|
| tatics                                  |                                                      |                                                                                          |                                  |       |      |      |      |
| B <sub>VDSS</sub>                       | Drain to Source Breakdown Voltage                    | I <sub>D</sub> = 250 μA, V <sub>GS</sub> = 0 V                                           |                                  | 500   | -    | -    | V    |
| ΔB <sub>VDSS</sub><br>/ ΔT <sub>J</sub> | Breakdown Voltage Temp. Coefficient                  | Reference to 25°C,<br>I <sub>D</sub> = 1 mA                                              |                                  | -     | 0.61 | -    | V/°( |
| r <sub>DS(ON)</sub>                     | Drain to Source On-Resistance                        | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 22 A                                            |                                  | -     | 0.11 | 0.12 | Ω    |
| V <sub>GS(th)</sub>                     | Gate Threshold Voltage                               | $V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$                                               |                                  | 2     | 3.15 | 4    | V    |
|                                         | Zana Oata Waltana Basin Oursell                      | V <sub>DS</sub> = 500 V                                                                  |                                  | -     | -    | 25   | ^    |
| I <sub>DSS</sub>                        | Zero Gate Voltage Drain Current                      | V <sub>GS</sub> = 0 V                                                                    | $T_{\rm C} = 150^{\rm o}{\rm C}$ | -     | -    | 250  | μΑ   |
| I <sub>GSS</sub>                        | Gate to Source Leakage Current                       | V <sub>GS</sub> = ±20 V                                                                  |                                  | -     | -    | ±100 | nA   |
| ynamics                                 |                                                      |                                                                                          |                                  |       |      |      |      |
| 9 <sub>fs</sub>                         | Forward Transconductance                             | V <sub>DS</sub> = 50 V, I <sub>D</sub> :                                                 | = 22 A                           | 11    | -    | -    | S    |
| Q <sub>g(TOT)</sub>                     | Total Gate Charge at 10V                             | V <sub>GS</sub> = 10 V,<br>V <sub>DS</sub> = 400 V,<br>I <sub>D</sub> = 44 A             |                                  | -     | 90   | 108  | nC   |
| Q <sub>gs</sub>                         | Gate to Source Gate Charge                           |                                                                                          |                                  | -     | 24   | 29   | nC   |
| Q <sub>ad</sub>                         | Gate to Drain "Miller" Charge                        |                                                                                          |                                  | -     | 31   | 37   | nC   |
| t <sub>d(ON)</sub>                      | Turn-On Delay Time                                   | $V_{DD} = 250 \text{ V},$ $I_D = 44 \text{ A},$ $R_G = 2.15 \Omega,$ $R_D = 5.68 \Omega$ |                                  | -\    | 16   | -    | ns   |
| t <sub>r</sub>                          | Rise Time                                            |                                                                                          |                                  | - \   | 84   | -    | ns   |
| t <sub>d(OFF)</sub>                     | Turn-Off Delay Time                                  |                                                                                          |                                  | -     | 45   | -    | ns   |
| t <sub>f</sub>                          | Fall Time                                            |                                                                                          |                                  | -     | 79   | -    | ns   |
| C <sub>ISS</sub>                        | Input Capacitance                                    | V <sub>DS</sub> = 25V, V <sub>GS</sub> = 0 V,<br>f = 1 MHz                               |                                  | -     | 5335 | -    | рF   |
| Coss                                    | Output Capacitance                                   |                                                                                          |                                  | -     | 645  | -    | рF   |
| C <sub>RSS</sub>                        | Reverse Transfer Capacitance                         |                                                                                          |                                  | -     | 40   | -    | рF   |
|                                         | e Characteristics                                    |                                                                                          |                                  |       |      |      | •    |
| E <sub>AS</sub>                         | Single Pulse Avalanche Energy <sup>2</sup>           |                                                                                          |                                  | 1500  | -    | -    | m.   |
| I <sub>AR</sub>                         | Avalanche Current                                    |                                                                                          |                                  | -     | -    | 44   | Α    |
| rain-Soເ                                | rce Diode Characteristics                            |                                                                                          |                                  |       |      |      |      |
| I <sub>S</sub>                          | Continuous Source Current<br>(Body Diode)            | MOSFET symbol showing the integral reverse p-n junction diode.                           |                                  | -/    | -    | 44   | А    |
| I <sub>SM</sub>                         | Pulsed Source Current <sup>1</sup> (Body Diode)      |                                                                                          |                                  | -     | -    | 176  | А    |
| V <sub>SD</sub>                         | Source to Drain Diode Voltage I <sub>SD</sub> = 44 A |                                                                                          | -                                | 0.900 | 1.2  | V    |      |

 $Q_{RR}$ 

1: Repetitive rating; pulse-width limited by maximum junction temperature. 2: Starting  $T_J$  = 25°C, L = 1.61 mH,  $I_{AS}$  = 44 A

Reverse Recovered Charge

Reverse Recovery Time

920

14

1100

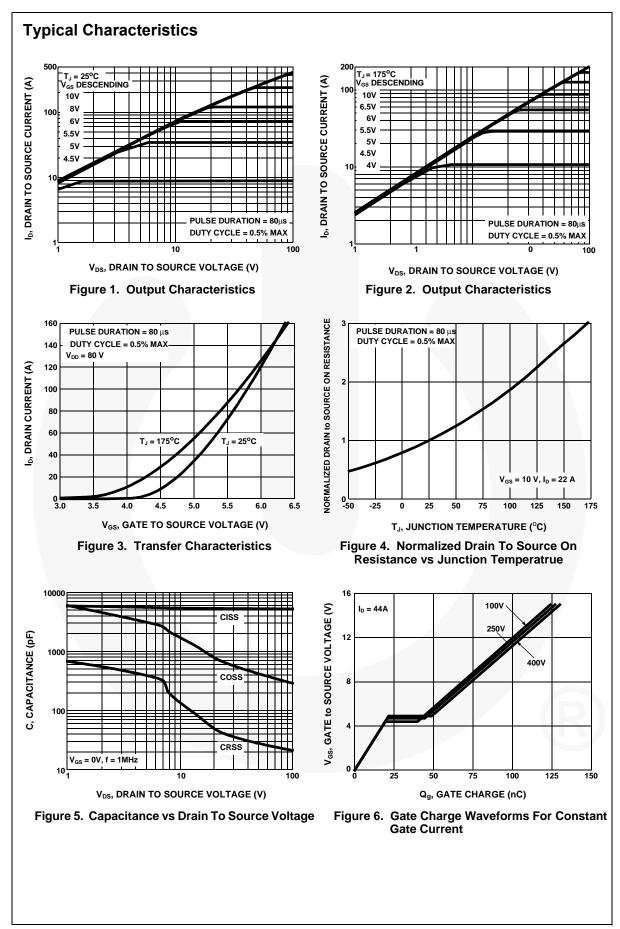
18

ns

μС

 $I_{SD} = 44 \text{ A}, dI_{SD}/dt = 100 \text{ A/}\mu\text{s}$ 

 $I_{SD} = 44 \text{ A}, dI_{SD}/dt = 100 \text{ A}/\mu\text{s}$ 



# T<sub>J</sub> = 175°C T<sub>J</sub> = 25°C T<sub>J</sub>

Typical Characteristics (Continued)

OPERATION IN THIS AREA

OPERATION IN THIS AREA

IOU

IOU

IOU

VDS, DRAIN TO SOURCE VOLTAGE (V)

Figure 7. Body Diode Forward Voltage vs Body Diode Current

V<sub>SD</sub>, SOURCE TO DRAIN VOLTAGE (V)

Figure 8. Maximum Safe Operating Area

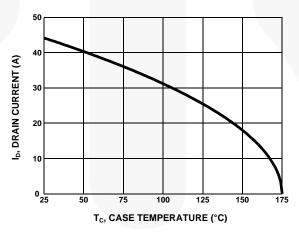


Figure 9. Maximum Drain Current vs Case Temperature

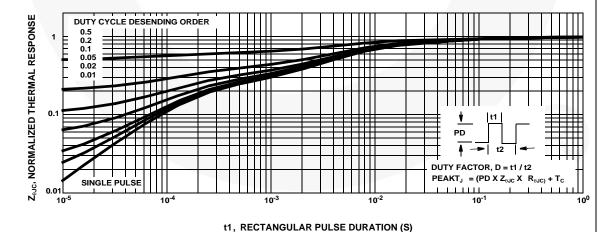


Figure 10. Normalized Transient Thermal Impedance, Junction to Case

# **Test Circuits and Waveforms**

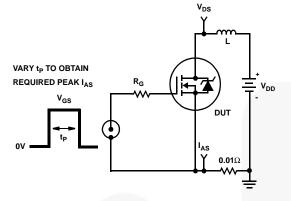


Figure 11. Unclamped Energy Test Circuit

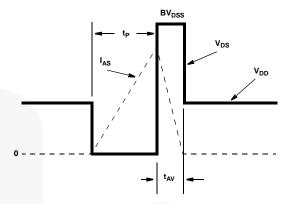


Figure 12. Unclamped Energy Waveforms

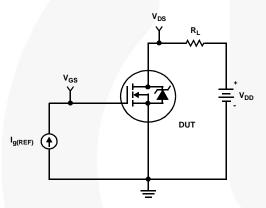


Figure 13. Gate Charge Test Circuit

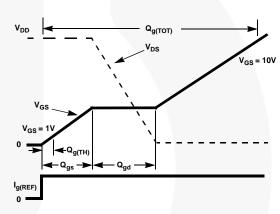


Figure 14. Gate Charge Waveforms

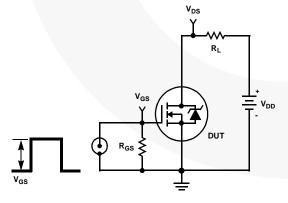


Figure 15. Switching Time Test Circuit

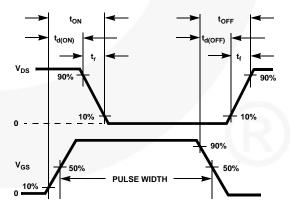
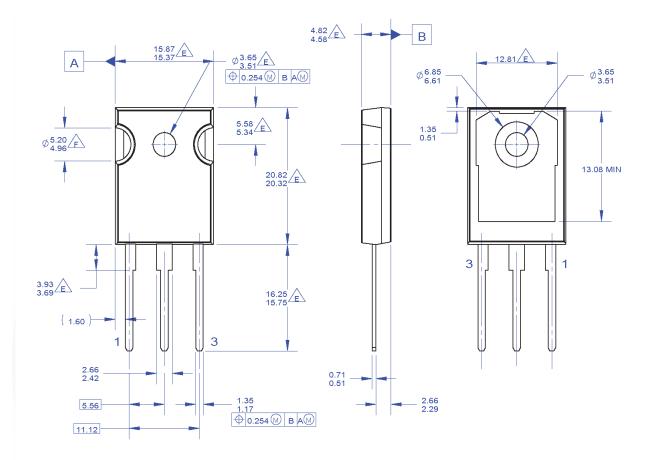


Figure 16. Switching Time Waveform

### **Mechanical Dimensions**



NOTES: UNLESS OTHERWISE SPECIFIED.

- A. PACKAGE REFERENCE: JEDEC TO-247, ISSUE E, VARIATION AB, DATED JUNE, 2004.
- DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- C. ALL DIMENSIONS ARE IN MILLIMETERS.
  D. DRAWING CONFORMS TO ASME Y14.5 1994
- E DOES NOT COMPLY JEDEC STANDARD VALUE
- NOTCH MAY BE SQUARE
- DRAWING FILENAME: MKT-TO247A03\_REV03

### Figure 17. TO-247, Molded, 3-Lead, Jedec Variation AB

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